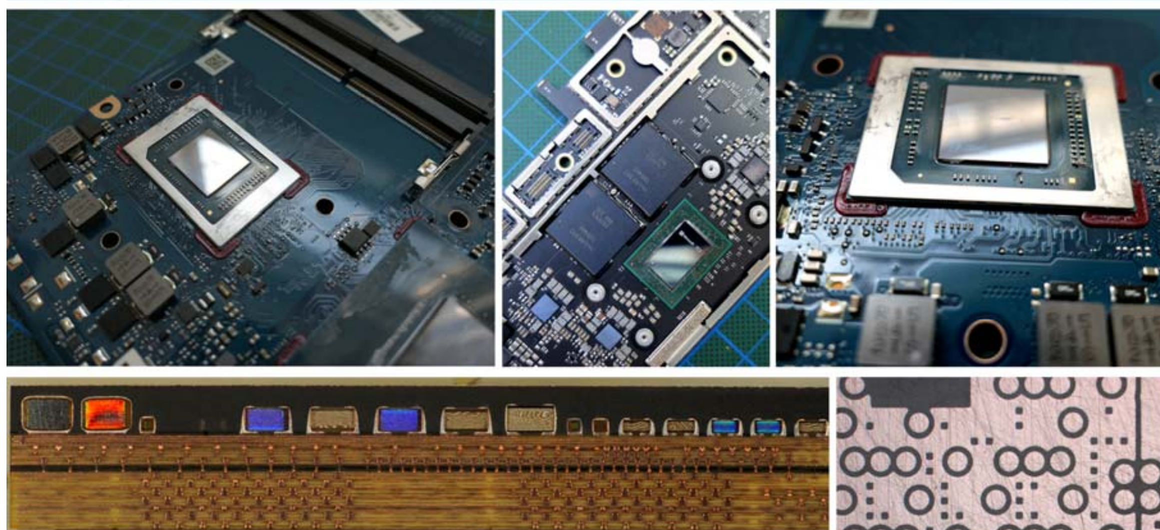
THE SEMICONDUCTOR AND PACKAGING REPORT

THIRD QUARTER • DECEMBER 2021



- State of the Semiconductor and Package Business
  - Review of the status of semiconductor shipments; Prismark's global economic and electronics forecast for 2021 and 2022; actual and forecast quarterly sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries. Includes a refresh of the packaging unit and forecast demand for IC components.
- Semiconductor and Packaging: Revised Outlook
  - Review of semiconductor market and package trends for 2021, 2022, and a revised outlook to 2025.
- System-in-Package (SiP) Market Update and Technology Trends
  - An updated Review of the fast growth SiP market including stacked CSP, PoP, RF modules, AiP, MEMS, Power SiP, and camera modules.
- Updates on China's Wafer Fabrication and Fabless CPU Suppliers
  - Summary of the world's leading ODM players for servers, all of whom are based in Taiwan and China.
- Company News: Semiconductor and Wafer Fabrication
  - News in the semiconductor and foundry businesses regarding leading players and new product offerings.
- Company News: Semiconductor Packaging
  - Recent developments in packaging at leading OSAT and captive assembly operations.

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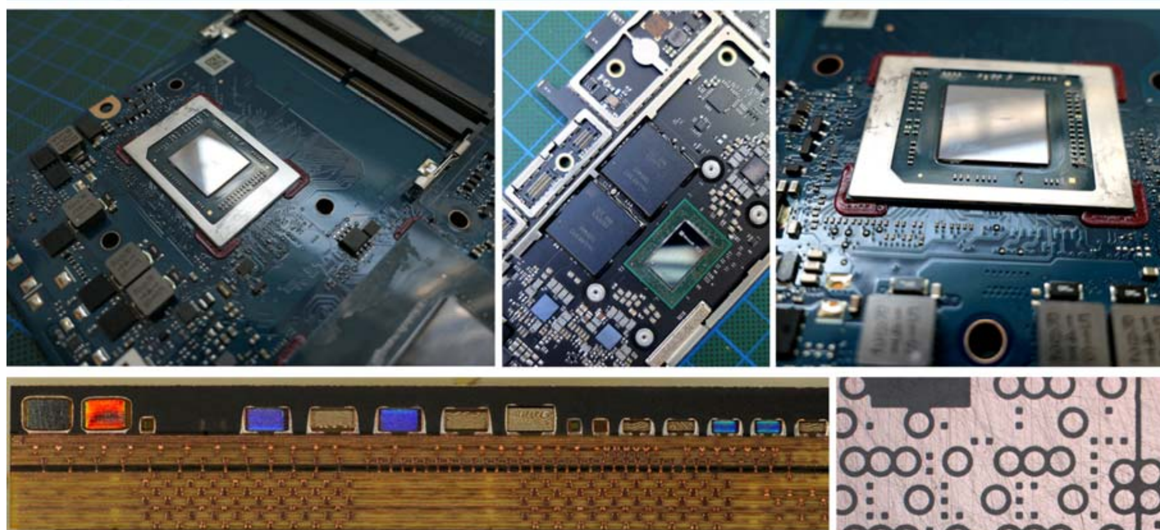
THE SEMICONDUCTOR AND PACKAGING REPORT

SECOND QUARTER • SEPTEMBER 2021



- State of the Semiconductor and Package Business
  - Review of the status of semiconductor shipments; Prismark's global economic and electronics forecast for 2021 and 2022; actual and forecast quarterly sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries
- Semiconductor and Packaging: Revised Outlook
  - Review of semiconductor market and package trends for 2021, 2022, and a revised outlook to 2025.
- Laminate-Based Packages and Package Substrates
  - An updated review of the fast growth package substrate market including wire bond BGA/CSP, FCCSP, FCBGA/LGA, and SiP. Includes trends and investments by leading suppliers to address rapid demand growth and alleviate shortage concerns.
- Updates on Server Market and Players in China and Taiwan
  - Summary of the world's leading ODM players for servers, all of whom are based in Taiwan and China.
- Company News: Semiconductor and Wafer Fabrication
  - News in the semiconductor and foundry businesses regarding leading players and new product offerings.
- Company News: Semiconductor Packaging
  - Recent developments in packaging at leading OSAT and captive assembly operations.

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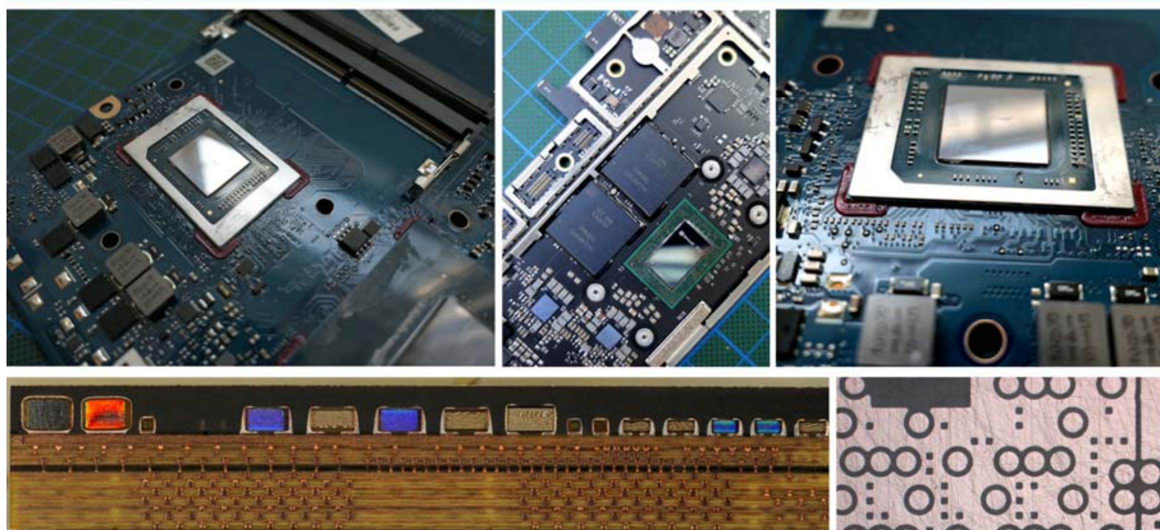
THE SEMICONDUCTOR AND PACKAGING REPORT

FIRST QUARTER • JUNE 2021



- State of the Semiconductor and Package Business
  – Review of the status of semiconductor shipments; Prismark's global economic and electronics forecast for 2020 and 2021, including COVID-19 impact; actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries.

- Semiconductor and Packaging: Revised Outlook
  – Review of Semiconductor market and package trends for 2020 and an outlook to 2025.

- Advanced Packaging for High-Performance Applications
  – An updated Review of leading advanced packages including WLCSP, FO-WLP, FO-MCM, 2.5D and emerging 3D approaches.

- Company News: Semiconductor and Wafer Fabrication
  – News in the semiconductor and foundry businesses regarding leading players and new product offerings.

- Company News: Semiconductor Packaging
  – Recent developments in packaging at leading OSAT and captive assembly operations.

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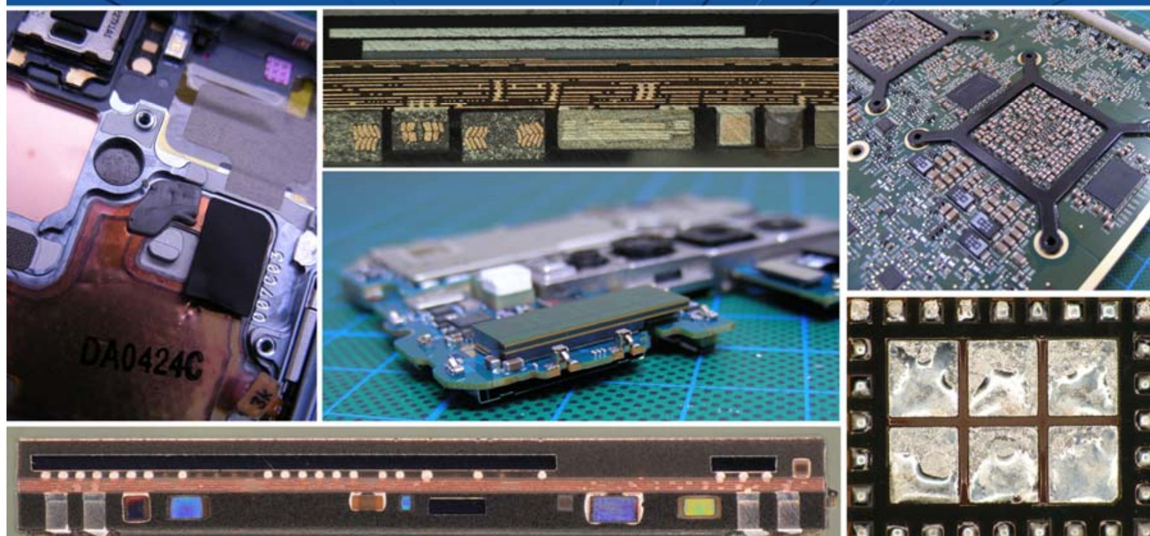
THE SEMICONDUCTOR AND PACKAGING REPORT

FOURTH QUARTER • MARCH 2021



- State of the Semiconductor and Package Business
  - Review of the status of semiconductor shipments; Prismark's global economic and electronics forecasts for 2020 and 2021, including COVID-19 impact; actual and forecasted sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries
- Semiconductor and Packaging: Five-Year Outlook
  - Review of semiconductor market and package trends for 2020 and an outlook to 2025
- Advanced Packaging for High-Performance Applications
  - An updated review of advanced packages including FCCSP and FCBGA substrate based solutions. This section will focus on emerging packages such as Intel EMIB, high-density fan-out approaches, 2.5D/silicon interposer, and forthcoming 3D packages for logic
- Update on Taiwan ODMs
  - Summary of Taiwan's major ODM suppliers, including latest investments, growth trends and technology development with a focus on notebook PC market and growth
- Company News: Semiconductor And Wafer Fabrication
  - News in the semiconductor and foundry businesses regarding leading players and new product offerings
- Company News: Semiconductor Packaging
  - Recent developments in packaging at leading OSAT and captive assembly operations

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Consultants to the Electronics Industry
Business Opportunity from Technology and
Market Changes

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